

APS-02-017



January 5, 2004

To: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Fr: George O. Saile, Reg. No. 19,572
28 Davis Avenue
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 10/690,996 10/22/03

Tan Kim Hwee et al.

FLIP CHIP PACKAGE USING NO-FLOW
UNDERFILL AND METHOD OF FABRICATION

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being
deposited with the United States Postal Service as first class
mail in an envelope addressed to: Commissioner for Patents,
P.O. Box 1450, Alexandria, VA 22313-1450, on January 27, 2004.

Stephen B. Ackerman, Reg.# 37761

Signature/Date Stephen B. Ackerman 1/27/04

U.S. Patent 6,441,487 to Elenius et al., "Chip Scale Package Using Large Ductile Solder Balls," describes a chip scale flip chip package utilizing large ductile solder balls.

U.S. Patent 6,429,530 to Chen, "Miniaturized Chip Scale Ball Grid Array Semiconductor Package," describes a miniaturized chip scale ball grid array package using a solder bumped chip carrier.

U.S. Patent 6,344,234 to Dalal et al., "Method for Forming Reflowed Solder Ball with Low Melting Point Metal Cap," describes a method for forming reflowed solder balls utilizing a metal cap of low temperature wetting material over the solder balls.

Sincerely,

A handwritten signature in black ink, appearing to read "Stephen B. Ackerman".

Stephen B. Ackerman,
Reg. No. 37761

Form PTO-1449

Doctor Mueller (Operator)

Application Number

APS-02-017

10/690,996

Application!

Tan Kim Hwee et al.

Filing Date

10/22/03

Group Art Unit



INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

U. S. PATENT DOCUMENTS

[illegible]

FOREIGN PATENT DOCUMENTS

[illegible]

OTHER DOCUMENTS (Including Author, Title, Date, Portion, Pages, Etc.)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.